


## APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

<b>Title of Invention</b>	METHOD FOR FORMING ROBUST SOLDER INTERCONNECT STRUCTURES BY REDUCING EFFECTS OF SEED LAYER UNDERETCHING		
Application Type :		regular, utility	
Attorney Docket Number :		FIS920030359US1	
Correspondence address:			
Customer Number:		29371	
Inventors Information:			
<u>Inventor 1:</u>			
<b>Applicant Authority Type:</b>	Inventor		
<b>Citizenship:</b>	US		
<b>Given Name:</b>	Kamalesh		
<b>Middle Name:</b>	K.		
<b>Family Name:</b>	Srivastava		
<b>Residence:</b>			
<b>City of Residence:</b>	Wappingers Falls		
<b>State of Residence:</b>	NY		
<b>Country of Residence:</b>	US		
<b>Address-1 of Mailing Address:</b>	319 Sheafe Road		
<b>Address-2 of Mailing Address:</b>			
<b>City of Mailing Address:</b>	Wappingers Falls		
<b>State of Mailing Address:</b>	NY		
<b>Postal Code of Mailing Address:</b>	12590		
<b>Country of Mailing Address:</b>	US		
<b>Phone:</b>			
<b>Fax:</b>			
<b>E-mail:</b>			
<u>Inventor 2:</u>			
<b>Applicant Authority Type:</b>	Inventor		
<b>Citizenship:</b>	US		
<b>Given Name:</b>	Subhash		

**Middle Name:** L.  
**Family Name:** Shinde  
**Residence:**  
**City of Residence:** Courtlandt Manor  
**State of Residence:** NY  
**Country of Residence:** US  
**Address-1 of Mailing Address:** 43 East Hill Road  
**Address-2 of Mailing Address:**  
**City of Mailing Address:** Courtlandt Manor  
**State of Mailing Address:** NY  
**Postal Code of Mailing Address:** 10567  
**Country of Mailing Address:** US  
**Phone:**  
**Fax:**  
**E-mail:**

Inventor 3:

**Applicant Authority Type:** Inventor  
**Citizenship:** US  
**Given Name:** Tien-Jen  
**Family Name:** Cheng  
**Residence:**  
**City of Residence:** Bedford  
**State of Residence:** NY  
**Country of Residence:** US  
**Address-1 of Mailing Address:** 75 Hickory Lane  
**Address-2 of Mailing Address:**  
**City of Mailing Address:** Bedford  
**State of Mailing Address:** NY  
**Postal Code of Mailing Address:** 10506  
**Country of Mailing Address:** US  
**Phone:**  
**Fax:**  
**E-mail:**

Inventor 4:

**Applicant Authority Type:** Inventor  
**Citizenship:** US  
**Given Name:** Sarah  
**Middle Name:** H.  
**Family Name:** Knickerbocker  
**Residence:**

**City of Residence:** Hopewell Junction  
**State of Residence:** NY  
**Country of Residence:** US  
**Address-1 of Mailing Address:** 208 Creamery Road  
**Address-2 of Mailing Address:**  
**City of Mailing Address:** Hopewell Junction  
**State of Mailing Address:** NY  
**Postal Code of Mailing Address:** 12533  
**Country of Mailing Address:** US  
**Phone:**  
**Fax:**  
**E-mail:**

Inventor 5:

**Applicant Authority Type:** Inventor  
**Citizenship:** CA  
**Given Name:** Roger  
**Middle Name:** A.  
**Family Name:** Quon  
**Residence:**  
**City of Residence:** Rhinebeck  
**State of Residence:** NY  
**Country of Residence:** US  
**Address-1 of Mailing Address:** 15 Rockefeller Lane  
**Address-2 of Mailing Address:**  
**City of Mailing Address:** Rhinebeck  
**State of Mailing Address:** NY  
**Postal Code of Mailing Address:** 12572  
**Country of Mailing Address:** US  
**Phone:**  
**Fax:**  
**E-mail:**

Inventor 6:

**Applicant Authority Type:** Inventor  
**Citizenship:** US  
**Given Name:** William  
**Middle Name:** E.  
**Family Name:** Sablinski  
**Residence:**  
**City of Residence:** Beacon  
**State of Residence:** NY

**Country of Residence:** US  
**Address-1 of Mailing Address:** 15 Monell Place  
**Address-2 of Mailing Address:**  
**City of Mailing Address:** Beacon  
**State of Mailing Address:** NY  
**Postal Code of Mailing Address:** 12508  
**Country of Mailing Address:** US  
**Phone:**  
**Fax:**  
**E-mail:**

Inventor 7:

**Applicant Authority Type:** Inventor  
**Citizenship:** US  
**Given Name:** Julie  
**Middle Name:** C.  
**Family Name:** Biggs  
**Residence:**  
**City of Residence:** Wappingers Falls  
**State of Residence:** NY  
**Country of Residence:** US  
**Address-1 of Mailing Address:** 15 Pye Lane  
**Address-2 of Mailing Address:**  
**City of Mailing Address:** Wappingers Falls  
**State of Mailing Address:** NY  
**Postal Code of Mailing Address:** 12590  
**Country of Mailing Address:** US  
**Phone:**  
**Fax:**  
**E-mail:**

Inventor 8:

**Applicant Authority Type:** Inventor  
**Citizenship:** US  
**Given Name:** David  
**Middle Name:** E.  
**Family Name:** Eichstadt  
**Residence:**  
**City of Residence:** Park Ridge  
**State of Residence:** IL  
**Country of Residence:** US  
**Address-1 of Mailing Address:** 1752 Park Ridge Pointe

**Address-2 of Mailing Address:****City of Mailing Address:** Park Ridge**State of Mailing Address:** IL**Postal Code of Mailing Address:** 60068**Country of Mailing Address:** US**Phone:****Fax:****E-mail:**Inventor 9:**Applicant Authority Type:** Inventor**Citizenship:** US**Given Name:** Jonathan**Middle Name:** H.**Family Name:** Griffith**Residence:****City of Residence:** Lagrangeville**State of Residence:** NY**Country of Residence:** US**Address-1 of Mailing Address:** 8 Budd Lane**Address-2 of Mailing Address:****City of Mailing Address:** Lagrangeville**State of Mailing Address:** NY**Postal Code of Mailing Address:** 12540**Country of Mailing Address:** US**Phone:****Fax:****E-mail:****Attorney Information:**

practitioner(s) at Customer Number:

29371



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.

Assignee 1:**Organization Name:** INTERNATIONAL BUSINESS MACHINES**Address-1 of Mailing Address:** CORPORATION**Address-2 of Mailing Address:** NEW ORCHARD ROAD**City of Mailing Address:** ARMONK

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